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In Re Application of:

Chen, et al.

Serial No.: 10/810,965

Filed: March 26, 2004

For: Novel Method to Improve Bump Reliability for  
Flip Chip Device

Confirmation No.: 9818

Examiner: Trinh, Hoa B.

Group Art Unit: 2814

TKHR Docket: 252016-2530

Top-Team: 0503-A30731US

**CERTIFICATE OF FACSIMILE TRANSMISSION UNDER 37 CFR §1.8**

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October 26, 2005  
Date

Hui Chin Barnhill  
Hui Chin Barnhill

**AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION WITH RCE**

Mail Stop RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

The FINAL Office Action mailed August 23, 2005 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.